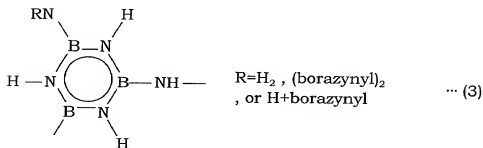
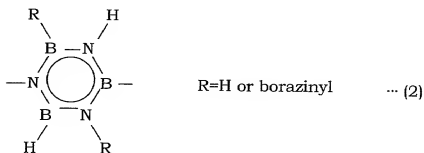
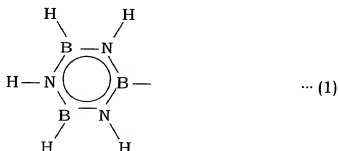


# WHAT IS CLAIMED IS

1. A low dielectric constant material having thermal resistance, comprising borazine skeletal molecules shown by the following formula (1), (2), or (3) in an inorganic or organic material molecule.



2. An insulation film between semiconductor layers, comprising the low dielectric constant material having thermal resistance of Claim 1.

3. A semiconductor device, comprising an insulation film between semiconductor layers comprising the low dielectric constant material having thermal resistance of Claim 1.